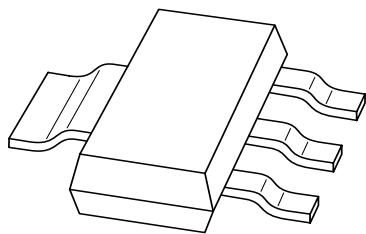


DATA SHEET



PZTA44

NPN high-voltage transistor

Product data sheet
Supersedes data of 1998 Nov 26

1999 May 21

NPN high-voltage transistor**PZTA44****FEATURES**

- Low current (max. 300 mA)
- High voltage (max. 400 V).

APPLICATIONS

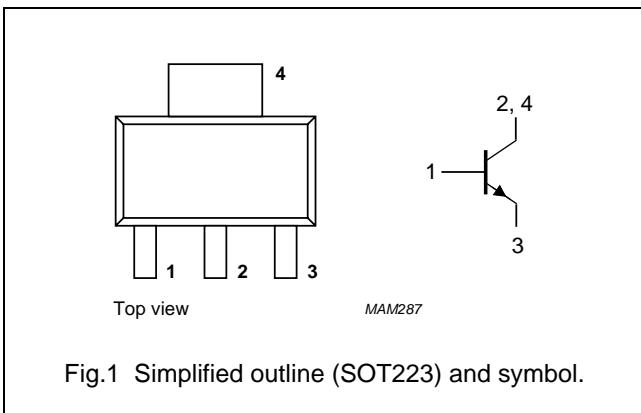
- Telecommunication.

DESCRIPTION

NPN high-voltage transistor in a SOT223 plastic package.

PINNING

PIN	DESCRIPTION
1	base
2, 4	collector
3	emitter

**LIMITING VALUES**

In accordance with the Absolute Maximum Rating System (IEC 134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V_{CBO}	collector-base voltage	open emitter	–	500	V
V_{CEO}	collector-emitter voltage	open base	–	400	V
V_{EBO}	emitter-base voltage	open collector	–	6	V
I_C	collector current (DC)		–	300	mA
I_{CM}	peak collector current		–	300	mA
I_{BM}	peak base current		–	100	mA
P_{tot}	total power dissipation	$T_{amb} \leq 25^\circ\text{C}$; note 1	–	1.35	W
T_{stg}	storage temperature		-65	+150	$^\circ\text{C}$
T_j	junction temperature		–	150	$^\circ\text{C}$
T_{amb}	operating ambient temperature		-65	+150	$^\circ\text{C}$

Note

1. Device mounted on a printed-circuit board, single-sided copper, tinplated, mounting pad for collector 1 cm². For other mounting conditions, see "Thermal considerations for SOT223 in the General Part of associated Handbook".

NPN high-voltage transistor

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THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
$R_{th\ j-a}$	thermal resistance from junction to ambient	note 1	91	K/W
$R_{th\ j-s}$	thermal resistance from junction to soldering point		10	K/W

Note

1. Device mounted on a printed-circuit board, single-sided copper, tinplated, mounting pad for collector 1 cm². For other mounting conditions, see "Thermal considerations for SOT223 in the General Part of associated Handbook".

CHARACTERISTICS

 $T_{amb} = 25^\circ C$ unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
I_{CBO}	collector cut-off current	$I_E = 0; V_{CB} = 400\text{ V}$	–	100	nA
		$I_E = 0; V_{CB} = 400\text{ V}; T_j = 150^\circ C$	–	10	μA
I_{EBO}	emitter cut-off current	$I_C = 0; V_{EB} = 4\text{ V}$	–	100	nA
h_{FE}	DC current gain	$V_{CE} = 10\text{ V}$ $I_C = 1\text{ mA}$ $I_C = 10\text{ mA}$ $I_C = 50\text{ mA}; \text{note 1}$ $I_C = 100\text{ mA}; \text{note 1}$	40 50 45 40	– 200 – –	
V_{CEsat}	collector-emitter saturation voltage	$I_C = 1\text{ mA}; I_B = 0.1\text{ mA}$	–	400	mV
		$I_C = 10\text{ mA}; I_B = 1\text{ mA}$	–	500	mV
		$I_C = 50\text{ mA}; I_B = 5\text{ mA}; \text{note 1}$	–	750	mV
V_{BEsat}	base-emitter saturation voltage	$I_C = 10\text{ mA}; I_B = 1\text{ mA}; \text{note 1}$	–	850	mV
C_c	collector capacitance	$I_E = i_e = 0; V_{CB} = 20\text{ V}; f = 1\text{ MHz}$	–	7	pF
C_e	emitter capacitance	$I_C = i_e = 0; V_{EB} = 500\text{ mV}; f = 1\text{ MHz}$	–	180	pF
f_T	transition frequency	$I_C = 10\text{ mA}; V_{CE} = 10\text{ V}; f = 100\text{ MHz}$	20	–	MHz

Note

1. Pulse test: $t_p \leq 300\text{ }\mu\text{s}; \delta \leq 0.02$.

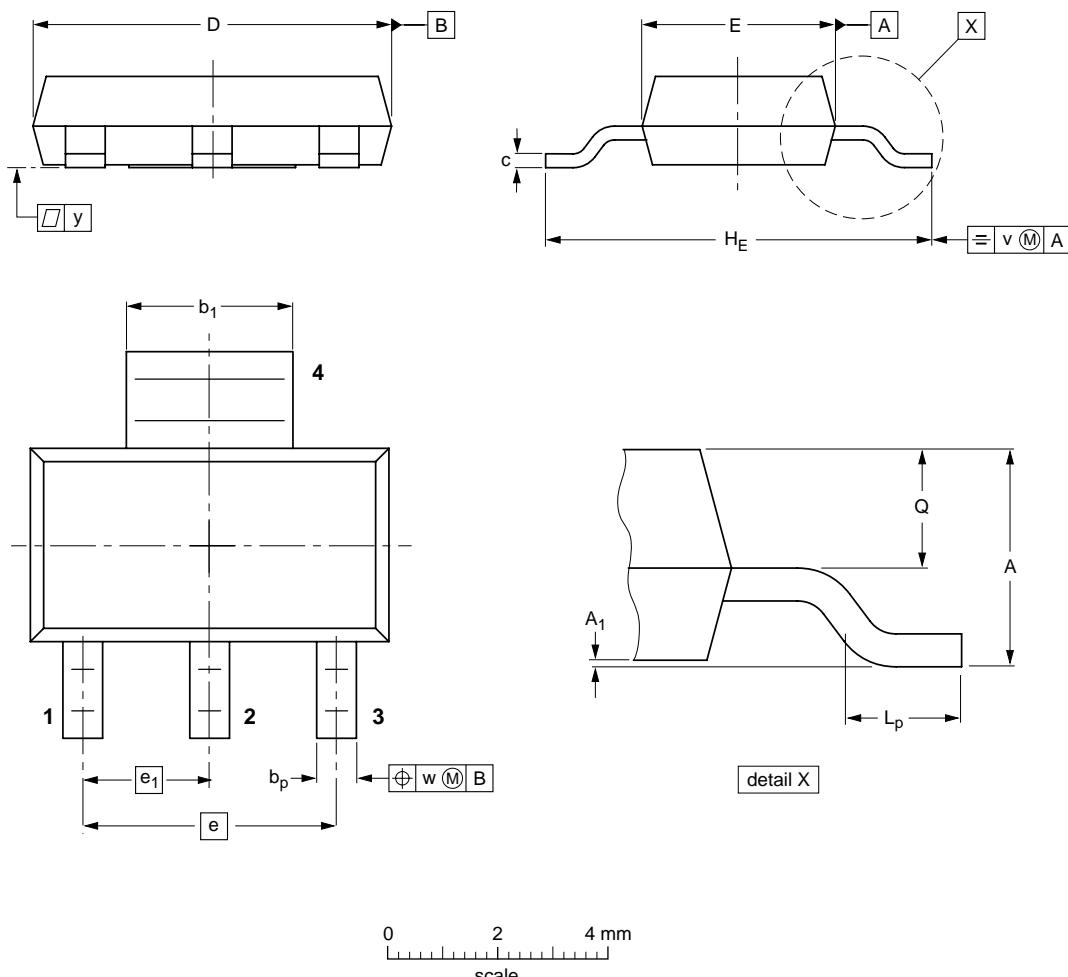
NPN high-voltage transistor

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PACKAGE OUTLINE

Plastic surface mounted package; collector pad for good heat transfer; 4 leads

SOT223



DIMENSIONS (mm are the original dimensions)

UNIT	A	A ₁	b _p	b ₁	c	D	E	e	e ₁	H _E	L _p	Q	v	w	y
mm	1.8	0.10	0.80	3.1	0.32	6.7	3.7	4.6	2.3	7.3	1.1	0.95	0.2	0.1	0.1
	1.5	0.01	0.60	2.9	0.22	6.3	3.3			6.7	0.7	0.85			

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ	SC-73		
SOT223						-97-02-28 99-09-13